

LOW-VOLTAGE MOTOR DRIVER IC

 Check for Samples: [DRV8832](#)

FEATURES

- **H-Bridge Voltage-Controlled Motor Driver**
 - Drives DC Motor, One Winding of a Stepper Motor, or Other Actuators/Loads
 - Efficient PWM Voltage Control for Constant Motor Speed With Varying Supply Voltages
 - Low MOSFET On-Resistance:
HS + LS 450 mΩ
- 1-A Maximum DC/RMS or Peak Drive Current
- 2.75-V to 6.8-V Operating Supply Voltage Range
- 300-nA (Typical) Sleep Mode Current
- Reference Voltage Output
- Current Limit Circuit

- **Fault Output**
- **Thermally Enhanced Surface Mount Packages**

APPLICATIONS

- **Battery-Powered:**
 - Printers
 - Toys
 - Robotics
 - Cameras
 - Phones
- **Small Actuators, Pumps, etc.**

DESCRIPTION

The DRV8832 provides an integrated motor driver solution for battery-powered toys, printers, and other low-voltage or battery-powered motion control applications. The device has one H-bridge driver, and can drive one DC motor or one winding of a stepper motor, as well as other loads like solenoids. The output driver block consists of N-channel and P-channel power MOSFET's configured as an H-bridge to drive the motor winding.

Provided with sufficient PCB heatsinking, the DRV8832 can supply up to 1-A of DC/RMS or peak output current. It operates on power supply voltages from 2.75 V to 6.8 V.

To maintain constant motor speed over varying battery voltages while maintaining long battery life, a PWM voltage regulation method is provided. An input pin allows programming of the regulated voltage. A built-in voltage reference output is also provided.

Internal protection functions are provided for over current protection, short circuit protection, under voltage lockout and overtemperature protection.

The DRV8832 also provides a current limit function to regulate the motor current during conditions like motor startup or stall, as well as a fault output pin to signal a host processor of a fault condition.

The DRV8832 is available in tiny 3-mm x 3-mm 10-pin MSOP and WSON packages with PowerPAD™ (Eco-friendly: RoHS & no Sb/Br).

ORDERING INFORMATION⁽¹⁾

| PACKAGE ⁽²⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|------------------------|--------------|-----------------------|------------------|
| PowerPAD™ (MSOP) - DGQ | Reel of 2500 | DRV8832DGQR | 8832 |
| | Tube of 80 | DRV8832DGQ | 8832 |
| PowerPAD™ (WSON) - DRC | Reel of 3000 | DRV8832DRCR | 8832 |
| | Reel of 250 | DRV8832DRCT | 8832 |

(1) For the most current packaging and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DEVICE INFORMATION

Functional Block Diagram

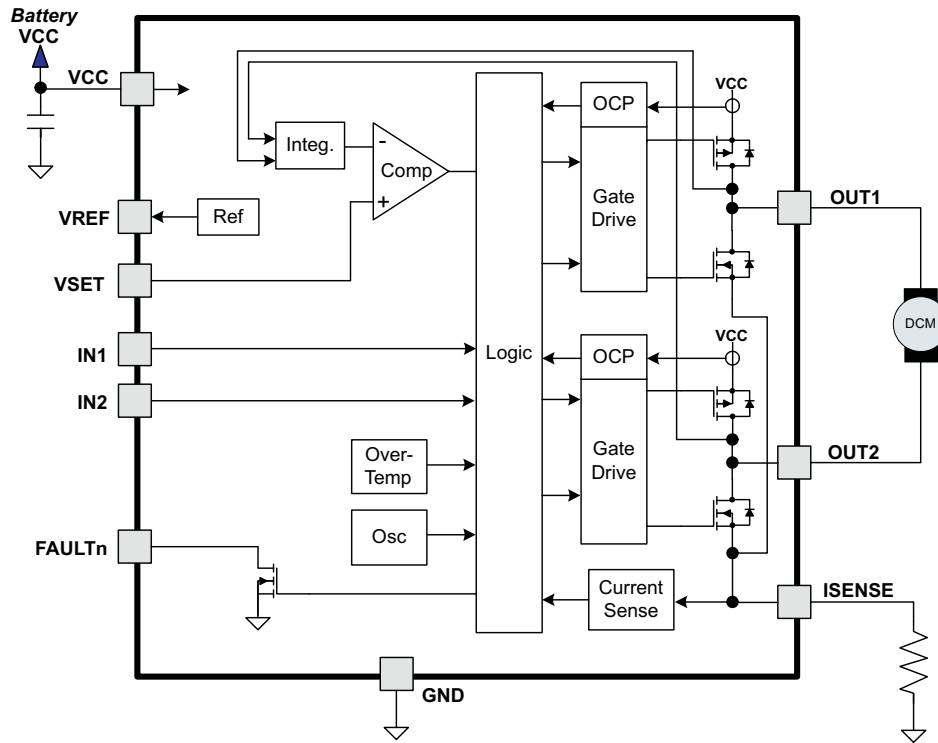
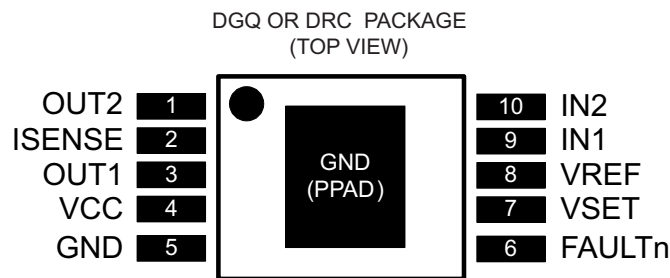


Table 1. TERMINAL FUNCTIONS

| NAME | PIN | I/O ⁽¹⁾ | DESCRIPTION | EXTERNAL COMPONENTS OR CONNECTIONS |
|--------|-----|--------------------|--------------------------|---|
| GND | 5 | - | Device ground | |
| VCC | 4 | - | Device and motor supply | Bypass to GND with a 0.1- μ F (minimum) ceramic capacitor. |
| IN1 | 9 | I | Bridge A input 1 | Logic high sets OUT1 high |
| IN2 | 10 | I | Bridge A input 2 | Logic high sets OUT2 high |
| VREF | 8 | O | Reference voltage output | Reference voltage output |
| VSET | 7 | I | Voltage set input | Input voltage sets output regulation voltage |
| FAULTn | 6 | OD | Fault output | Open-drain output driven low if fault condition present |
| OUT1 | 3 | O | Bridge output 1 | Connect to motor winding |
| OUT2 | 1 | O | Bridge output 2 | Connect to motor winding |
| ISENSE | 2 | IO | Current sense resistor | Connect current sense resistor to GND. Resistor value sets current limit level. |

(1) Directions: I = input, O = output, OZ = tri-state output, OD = open-drain output, IO = input/output


ABSOLUTE MAXIMUM RATINGS⁽¹⁾⁽²⁾

| | VALUE | UNIT |
|---|-------------------------------|------|
| VCC Power supply voltage range | -0.3 to 7 | V |
| Input pin voltage range | -0.5 to 7 | V |
| Peak motor drive output current ⁽³⁾ | Internally limited | A |
| Continuous motor drive output current ⁽³⁾ | 1 | A |
| Continuous total power dissipation | See Dissipation Ratings table | |
| T _J Operating virtual junction temperature range | -40 to 150 | °C |
| T _{stg} Storage temperature range | -60 to 150 | °C |

- (1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.
- (3) Power dissipation and thermal limits must be observed.

THERMAL INFORMATION

| THERMAL METRIC ⁽¹⁾ | | DRV8832 | DRV8832 | UNITS |
|-------------------------------|---|---------|---------|-------|
| | | DGQ | DRC | |
| | | 10 PINS | 10 PINS | |
| θ_{JA} | Junction-to-ambient thermal resistance ⁽²⁾ | 69.3 | 50.2 | °C/W |
| θ_{JcTop} | Junction-to-case (top) thermal resistance ⁽³⁾ | 63.5 | 78.4 | |
| θ_{JB} | Junction-to-board thermal resistance ⁽⁴⁾ | 51.6 | 18.8 | |
| ψ_{JT} | Junction-to-top characterization parameter ⁽⁵⁾ | 1.5 | 1.1 | |
| ψ_{JB} | Junction-to-board characterization parameter ⁽⁶⁾ | 23.2 | 17.9 | |
| θ_{JcBot} | Junction-to-case (bottom) thermal resistance ⁽⁷⁾ | 9.5 | 5.1 | |

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).
- (2) The junction-to-ambient thermal resistance under natural convection is obtained in a simulation on a JEDEC-standard, high-K board, as specified in JESD51-7, in an environment described in JESD51-2a.
- (3) The junction-to-case (top) thermal resistance is obtained by simulating a cold plate test on the package top. No specific JEDEC-standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.
- (4) The junction-to-board thermal resistance is obtained by simulating in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8.
- (5) The junction-to-top characterization parameter, ψ_{JT} , estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA} , using a procedure described in JESD51-2a (sections 6 and 7).
- (6) The junction-to-board characterization parameter, ψ_{JB} , estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA} , using a procedure described in JESD51-2a (sections 6 and 7).
- (7) The junction-to-case (bottom) thermal resistance is obtained by simulating a cold plate test on the exposed (power) pad. No specific JEDEC standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

| | | MIN | NOM | MAX | UNIT |
|-----------|---|------|-----|-----|------|
| V_{CC} | Motor power supply voltage range | 2.75 | | 6.8 | V |
| I_{OUT} | Continuous or peak H-bridge output current ⁽¹⁾ | 0 | | 1 | A |

- (1) Power dissipation and thermal limits must be observed.

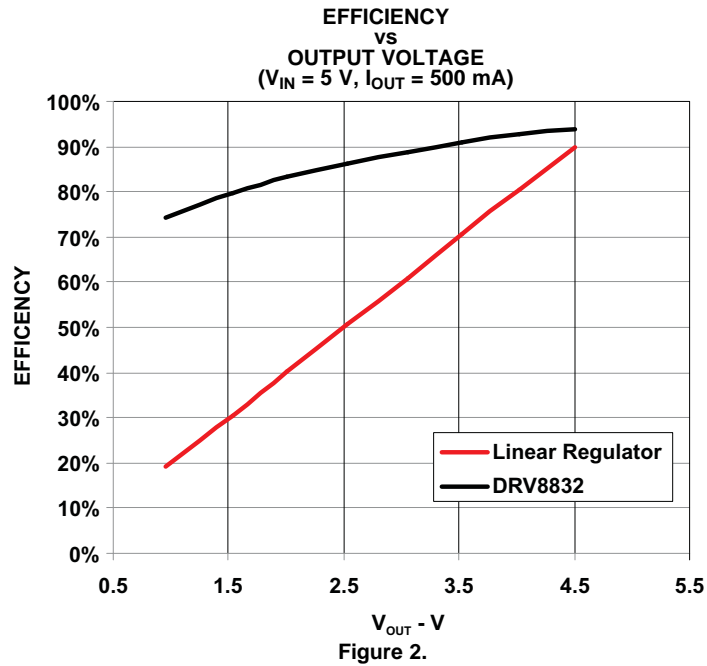
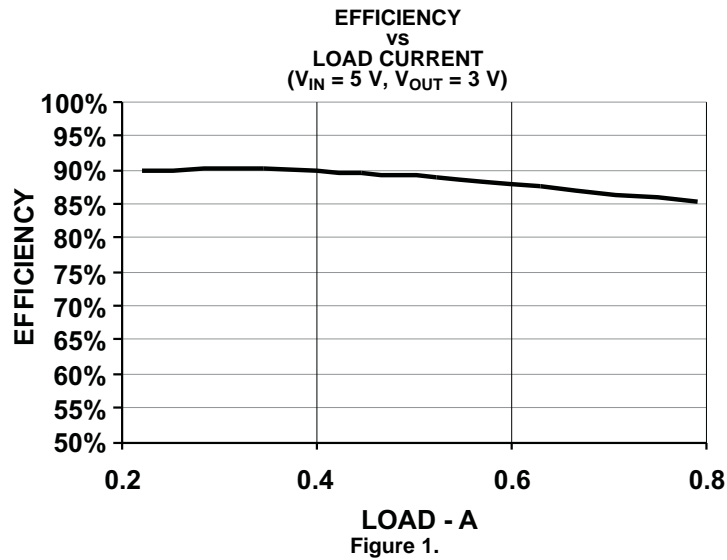
ELECTRICAL CHARACTERISTICS

 $V_{CC} = 2.75\text{ V to }6.8\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------------------------------|--|--|---------------------|---------|----------------------|------------------|
| POWER SUPPLIES | | | | | | |
| I_{VCC} | VCC operating supply current | $V_{CC} = 5\text{ V}$ | | 1.4 | 2 | mA |
| I_{VCCQ} | VCC sleep mode supply current | $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ | | 0.3 | 1 | μA |
| V_{UVLO} | VCC undervoltage lockout voltage | V_{CC} rising | | 2.575 | 2.75 | V |
| | | V_{CC} falling | | 2.47 | | |
| LOGIC-LEVEL INPUTS | | | | | | |
| V_{IL} | Input low voltage | | | | $0.25 \times V_{CC}$ | V |
| V_{IH} | Input high voltage | | $0.5 \times V_{CC}$ | | | V |
| I_{IL} | Input low current | $V_{IN} = 0$ | -10 | | 10 | μA |
| I_{IH} | Input high current | $V_{IN} = 3.3\text{ V}$ | | | 50 | μA |
| LOGIC-LEVEL OUTPUTS (FAULTn) | | | | | | |
| V_{OL} | Output low voltage | $V_{CC} = 5\text{ V}$, $I_{OL} = 4\text{ mA}^{(1)}$ | | 0.5 | | V |
| H-BRIDGE FETS | | | | | | |
| $R_{DS(ON)}$ | HS FET on resistance | $V_{CC} = 5\text{ V}$, $I_O = 0.8\text{ A}$, $T_J = 85^\circ\text{C}$ | | 290 | 400 | m Ω |
| | | $V_{CC} = 5\text{ V}$, $I_O = 0.8\text{ A}$, $T_J = 25^\circ\text{C}$ | | 250 | | |
| $R_{DS(ON)}$ | LS FET on resistance | $V_{CC} = 5\text{ V}$, $I_O = 0.8\text{ A}$, $T_J = 85^\circ\text{C}$ | | 230 | 320 | m Ω |
| | | $V_{CC} = 5\text{ V}$, $I_O = 0.8\text{ A}$, $T_J = 25^\circ\text{C}$ | | 200 | | |
| I_{OFF} | Off-state leakage current | | -20 | | 20 | μA |
| MOTOR DRIVER | | | | | | |
| t_R | Rise time | $V_{CC} = 3\text{ V}$, load = $4\ \Omega$ | 50 | | 300 | ns |
| t_F | Fall time | $V_{CC} = 3\text{ V}$, load = $4\ \Omega$ | 50 | | 300 | ns |
| f_{SW} | Internal PWM frequency | | | 44.5 | | kHz |
| PROTECTION CIRCUITS | | | | | | |
| I_{OCP} | Overcurrent protection trip level | | 1.3 | | 3 | A |
| t_{OCP} | OCP deglitch time | | | 2 | | μs |
| T_{TSD} | Thermal shutdown temperature | Die temperature ⁽¹⁾ | 150 | 160 | 180 | $^\circ\text{C}$ |
| VOLTAGE CONTROL | | | | | | |
| V_{REF} | Reference output voltage | | 1.235 | 1.285 | 1.335 | V |
| ΔV_{LINE} | Line regulation | $V_{CC} = 3.3\text{ V to }6\text{ V}$, $V_{OUT} = 3\text{ V}^{(1)}$ $I_{OUT} = 500\text{ mA}$ | | ± 1 | | % |
| ΔV_{LOAD} | Load regulation | $V_{CC} = 5\text{ V}$, $V_{OUT} = 3\text{ V}$ $I_{OUT} = 200\text{ mA to }800\text{ mA}^{(1)}$ | | ± 1 | | % |
| CURRENT LIMIT | | | | | | |
| V_{ILIM} | Current limit sense voltage | | 160 | 200 | 240 | mV |
| t_{LIM} | Current limit fault deglitch time | | | 275 | | ms |
| R_{ISEN} | Current limit set resistance (external resistor value) | | 0 | | 1 | Ω |

(1) Not production tested.

TYPICAL PERFORMANCE GRAPHS



FUNCTIONAL DESCRIPTION

Power Supervisor

The DRV8832 is capable of entering a low-power sleep mode by bringing both of the INx control inputs logic low. The outputs will be disabled Hi-Z.

In order to exit the sleep mode, bring either or both of the INx inputs logic high. This will enable the H-bridges. When exiting the sleep mode, the FAULTn pin will pulse low.

PWM Motor Driver

The DRV8832 contains an H-bridge motor driver with PWM voltage-control circuitry with current limit circuitry. A block diagram of the motor control circuitry is shown below.

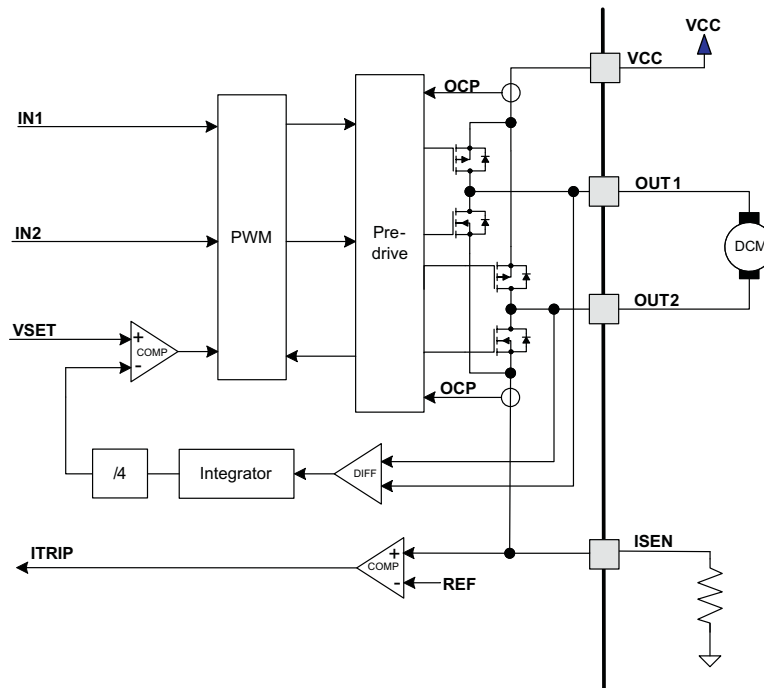


Figure 3. Motor Control Circuitry

Bridge Control

The IN1 and IN2 control pins enable the H-bridge outputs. The following table shows the logic:

Table 2. H-Bridge Logic

| IN1 | IN2 | OUT1 | OUT2 | Function |
|-----|-----|------|------|-------------|
| 0 | 0 | Z | Z | Sleep/Coast |
| 0 | 1 | L | H | Reverse |
| 1 | 0 | H | L | Forward |
| 1 | 1 | H | H | Brake |

When both inputs are low, the output drivers are disabled and the device is placed into a low-power sleep state. The current limit fault condition (if present) is also cleared. Note that when transitioning from either brake or sleep mode to forward or reverse, the voltage control PWM starts at zero duty cycle. The duty cycle slowly ramps up to the commanded voltage. This can take up to 12 ms to go from sleep to 100% duty cycle. Because of this, high-speed PWM signals cannot be applied to the IN1 and IN2 pins. To control motor speed, use the VSET pin as described below.

Because of the sleep mode functionality described previously, when applying an external PWM to the DRV8832, hold one input logic high while applying a PWM signal to the other. If the logic input is held low instead, then the device will cycle in and out of sleep mode, causing the FAULTn pin to pulse low on every sleep mode exit.

Voltage Regulation

The DRV8832 provides the ability to regulate the voltage applied to the motor winding. This feature allows constant motor speed to be maintained even when operating from a varying supply voltage such as a discharging battery.

The DRV8832 uses a pulse-width modulation (PWM) technique instead of a linear circuit to minimize current consumption and maximize battery life.

The circuit monitors the voltage difference between the output pins and integrates it, to get an average DC voltage value. This voltage is divided by 4 and compared to the VSET pin voltage. If the averaged output voltage (divided by 4) is lower than VSET, the duty cycle of the PWM output is increased; if the averaged output voltage (divided by 4) is higher than VSET, the duty cycle is decreased.

During PWM regulation, the H-bridge is enabled to drive current through the motor winding during the PWM on time. This is shown in the diagram below as case 1. The current flow direction shown indicates the state when IN1 is high and IN2 is low.

Note that if the programmed output voltage is greater than the supply voltage, the device will operate at 100% duty cycle and the voltage regulation feature will be disabled. In this mode the device behaves as a conventional H-bridge driver.

During the PWM off time, winding current is re-circulated by enabling both of the high-side FETs in the bridge. This is shown as case 2 below.

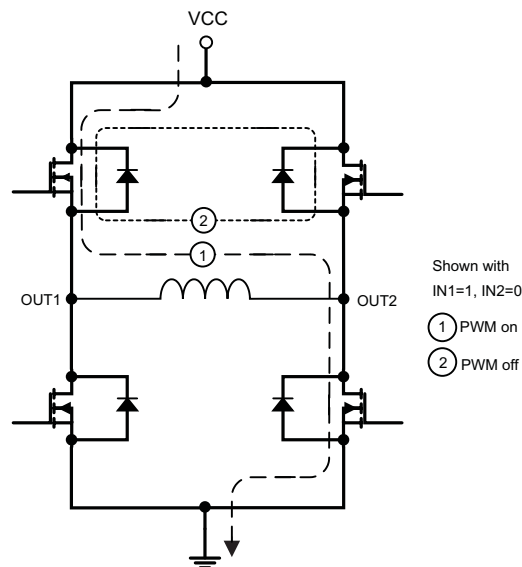


Figure 4. Voltage Regulation

Reference Output

The DRV8832 includes a reference voltage output that can be used to set the motor voltage. Typically for a constant-speed application, VSET is driven from VREF through a resistor divider to provide a voltage equal to 1/4 the desired motor drive voltage.

For example, if VREF is connected directly to VSET, the voltage will be regulated at 5.14 V. If the desired motor voltage is 3 V, VREF should be 0.75 V. This can be obtained with a voltage divider using 53 k Ω from VREF to VSET, and 75 k Ω from VSET to GND.

Current Limit

A current limit circuit is provided to protect the system in the event of an overcurrent condition, such as what would be encountered if driving a DC motor at start-up or with an abnormal mechanical load (stall condition).

The motor current is sensed by monitoring the voltage across an external sense resistor. When the voltage exceeds a reference voltage of 200 mV for more than approximately 3 μ s, the PWM duty cycle is reduced to limit the current through the motor to this value. This current limit allows for starting the motor while controlling the current.

If the current limit condition persists for some time, it is likely that a fault condition has been encountered, such as the motor being run into a stop or a stalled condition. An overcurrent event must persist for approximately 275 ms before the fault is registered. After approximately 275 ms, a fault signaled to the host by driving the FAULTn signal low. Operation of the motor driver will continue.

The current limit fault condition is cleared by taking both IN1 and IN2 low to disable the motor current, or by removing and re-applying power to the device.

The resistor used to set the current limit must be less than 1 Ω . Its value may be calculated as follows:

$$R_{ISENSE} = \frac{200 \text{ mV}}{I_{LIMIT}} \quad (1)$$

Where:

R_{ISENSE} is the current sense resistor value.

I_{LIMIT} is the desired current limit (in mA).

If the current limit feature is not needed, the ISENSE pin may be directly connected to ground.

Protection Circuits

The DRV8832 is fully protected against undervoltage, overcurrent and overtemperature events.

Overcurrent Protection (OCP)

An analog current limit circuit on each FET limits the current through the FET by removing the gate drive. If this analog current limit persists for longer than the OCP time, all FETs in the H-bridge will be disabled, and the FAULTn signal will be driven low. The device will remain disabled until VCC is removed and re-applied.

Overcurrent conditions are sensed independently on both high and low side devices. A short to ground, supply, or across the motor winding will all result in an overcurrent shutdown. Note that OCP is independent of the current limit function, which is typically set to engage at a lower current level; the OCP function is intended to prevent damage to the device under abnormal (e.g., short-circuit) conditions.

Thermal Shutdown (TSD)

If the die temperature exceeds safe limits, all FETs in the H-bridge will be disabled and the FAULTn signal will be driven low. Once the die temperature has fallen to a safe level operation will automatically resume.

Undervoltage Lockout (UVLO)

If at any time the voltage on the VCC pins falls below the undervoltage lockout threshold voltage, all circuitry in the device will be disabled, the FAULTn signal will be driven low, and internal logic will be reset. Operation will resume when VCC rises above the UVLO threshold.

THERMAL INFORMATION

Thermal Protection

The DRV8832 has thermal shutdown (TSD) as described above. If the die temperature exceeds approximately 160°C, the device will be disabled until the temperature drops to a safe level.

Any tendency of the device to enter TSD is an indication of either excessive power dissipation, insufficient heatsinking, or too high an ambient temperature.

Power Dissipation

Power dissipation in the DRV8832 is dominated by the power dissipated in the output FET resistance, or $R_{DS(ON)}$. Average power dissipation when running a stepper motor can be roughly estimated by [Equation 2](#).

$$P_{TOT} = 2 \cdot R_{DS(ON)} \cdot (I_{OUT(RMS)})^2 \quad (2)$$

where P_{TOT} is the total power dissipation, $R_{DS(ON)}$ is the resistance of each FET, and $I_{OUT(RMS)}$ is the RMS output current being applied to each winding. $I_{OUT(RMS)}$ is equal to the approximately 0.7x the full-scale output current setting. The factor of 2 comes from the fact that at any instant two FETs are conducting winding current for each winding (one high-side and one low-side).

The maximum amount of power that can be dissipated in the device is dependent on ambient temperature and heatsinking.

Note that $R_{DS(ON)}$ increases with temperature, so as the device heats, the power dissipation increases. This must be taken into consideration when sizing the heatsink.

Heatsinking

The PowerPAD™ package uses an exposed pad to remove heat from the device. For proper operation, this pad must be thermally connected to copper on the PCB to dissipate heat. On a multi-layer PCB with a ground plane, this can be accomplished by adding a number of vias to connect the thermal pad to the ground plane. On PCBs without internal planes, copper area can be added on either side of the PCB to dissipate heat. If the copper area is on the opposite side of the PCB from the device, thermal vias are used to transfer the heat between top and bottom layers.

For details about how to design the PCB, refer to TI application report [SLMA002](#), "PowerPAD™ Thermally Enhanced Package" and TI application brief [SLMA004](#), "PowerPAD™ Made Easy", available at www.ti.com.

In general, the more copper area that can be provided, the more power can be dissipated.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|---------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| DRV8832DGQ | ACTIVE | MSOP-PowerPAD | DGQ | 10 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 85 | 8832 | Samples |
| DRV8832DGQR | ACTIVE | MSOP-PowerPAD | DGQ | 10 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAUAG | Level-2-260C-1 YEAR | -40 to 85 | 8832 | Samples |
| DRV8832DRCR | ACTIVE | VSON | DRC | 10 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | 8832 | Samples |
| DRV8832DRCT | ACTIVE | VSON | DRC | 10 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | 8832 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF DRV8832 :

- Automotive: [DRV8832-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|----------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| DRV8832DGQR | MSOP-Power PAD | DGQ | 10 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| DRV8832DRCR | VSON | DRC | 10 | 3000 | 330.0 | 12.4 | 3.3 | 3.3 | 1.1 | 8.0 | 12.0 | Q2 |
| DRV8832DRCT | VSON | DRC | 10 | 250 | 180.0 | 12.4 | 3.3 | 3.3 | 1.1 | 8.0 | 12.0 | Q2 |

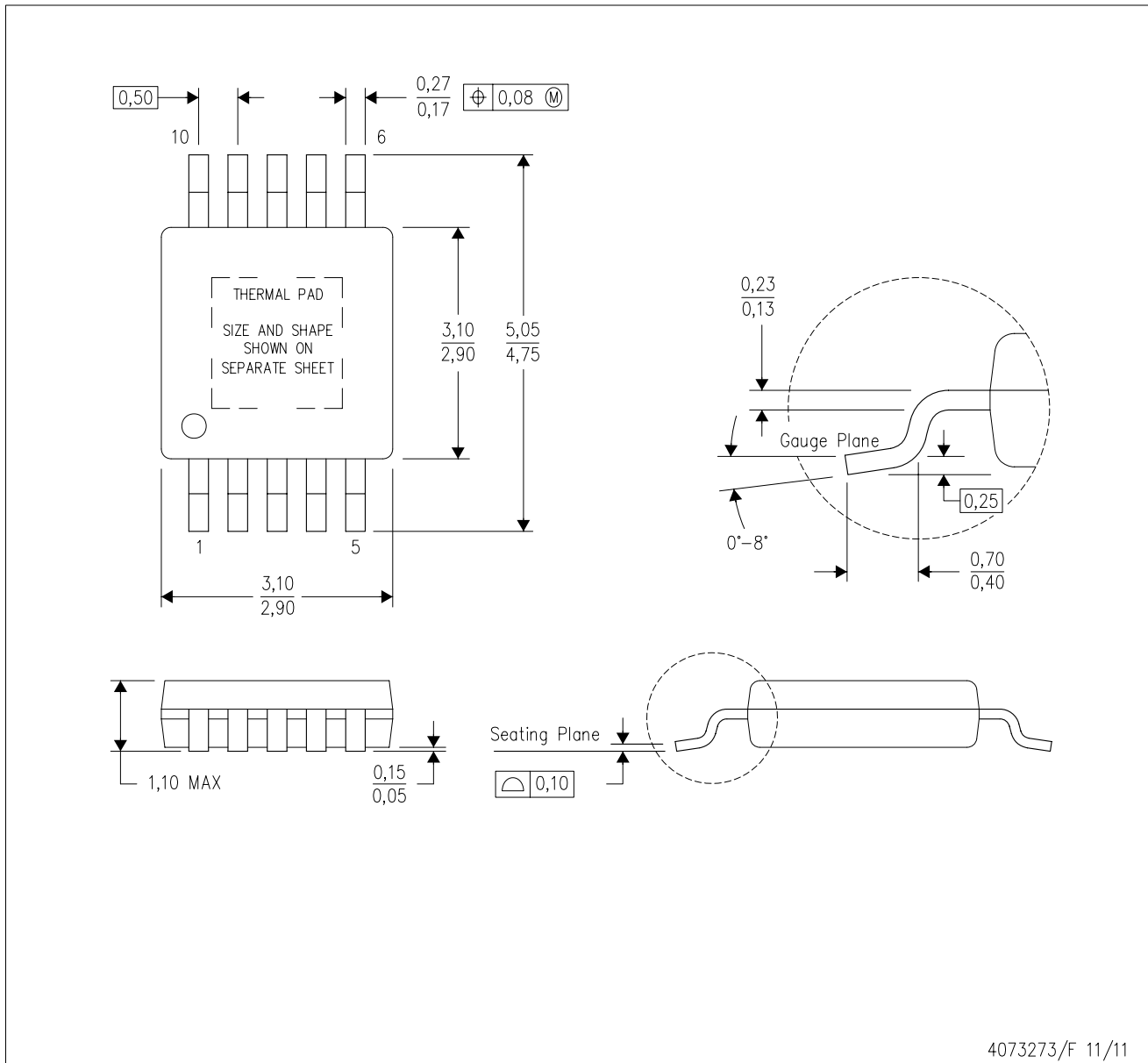
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|---------------|-----------------|------|------|-------------|------------|-------------|
| DRV8832DGQR | MSOP-PowerPAD | DGQ | 10 | 2500 | 367.0 | 367.0 | 35.0 |
| DRV8832DRCR | VSON | DRC | 10 | 3000 | 367.0 | 367.0 | 35.0 |
| DRV8832DRCT | VSON | DRC | 10 | 250 | 210.0 | 185.0 | 35.0 |

DGQ (S-PDSO-G10)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Falls within JEDEC MO-187 variation BA-T.

PowerPAD is a trademark of Texas Instruments.

DGQ (S-PDSO-G10)

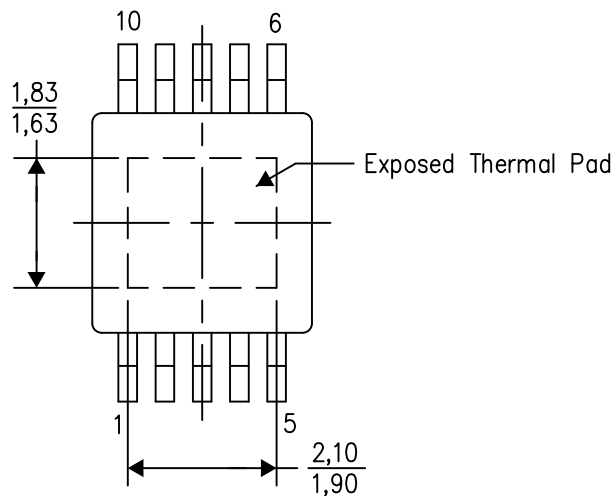
PowerPAD™ PLASTIC SMALL OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

Exposed Thermal Pad Dimensions

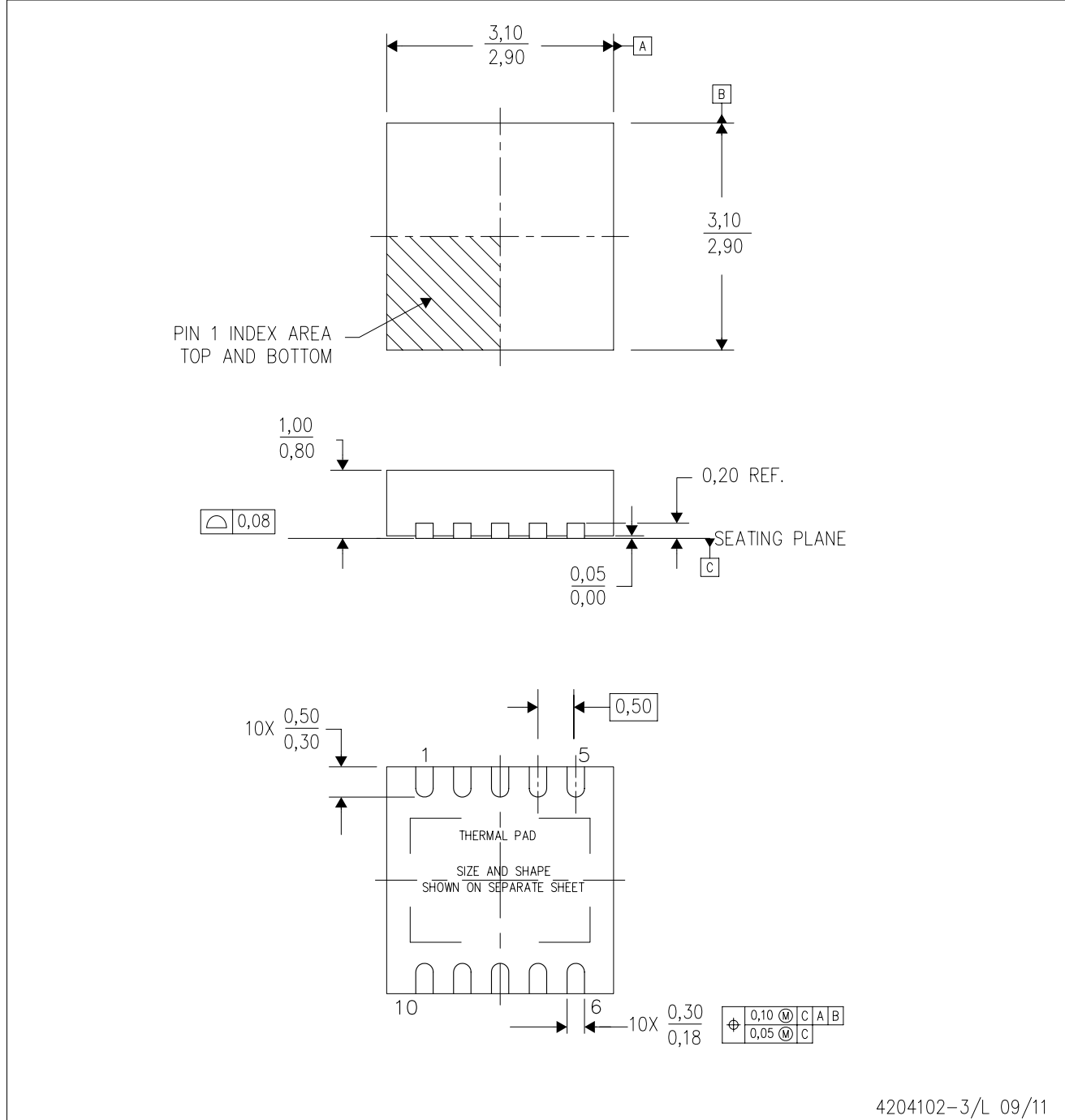
4206324-6/H 12/14

NOTE: A. All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

DRC (S-PVSON-N10)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Small Outline No-Lead (SON) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance, if present.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions, if present

THERMAL PAD MECHANICAL DATA

DRC (S-PVSON-N10)

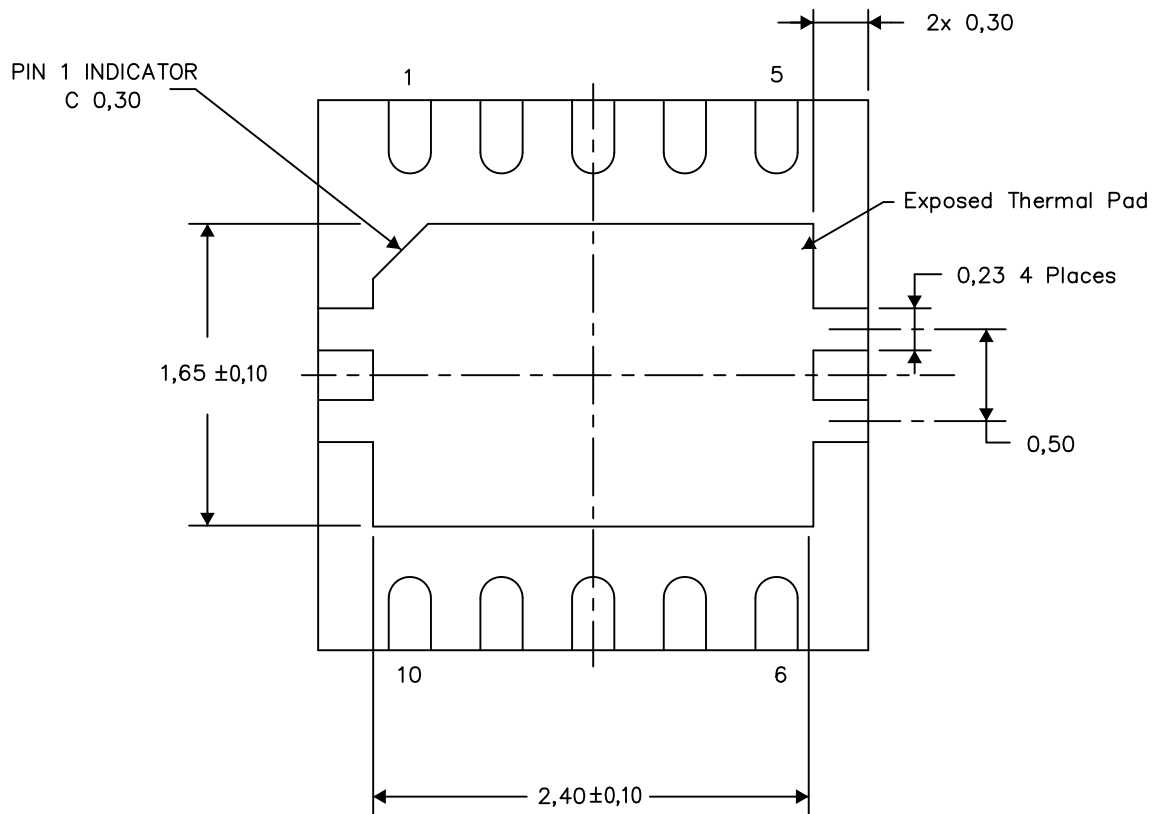
PLASTIC SMALL OUTLINE NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

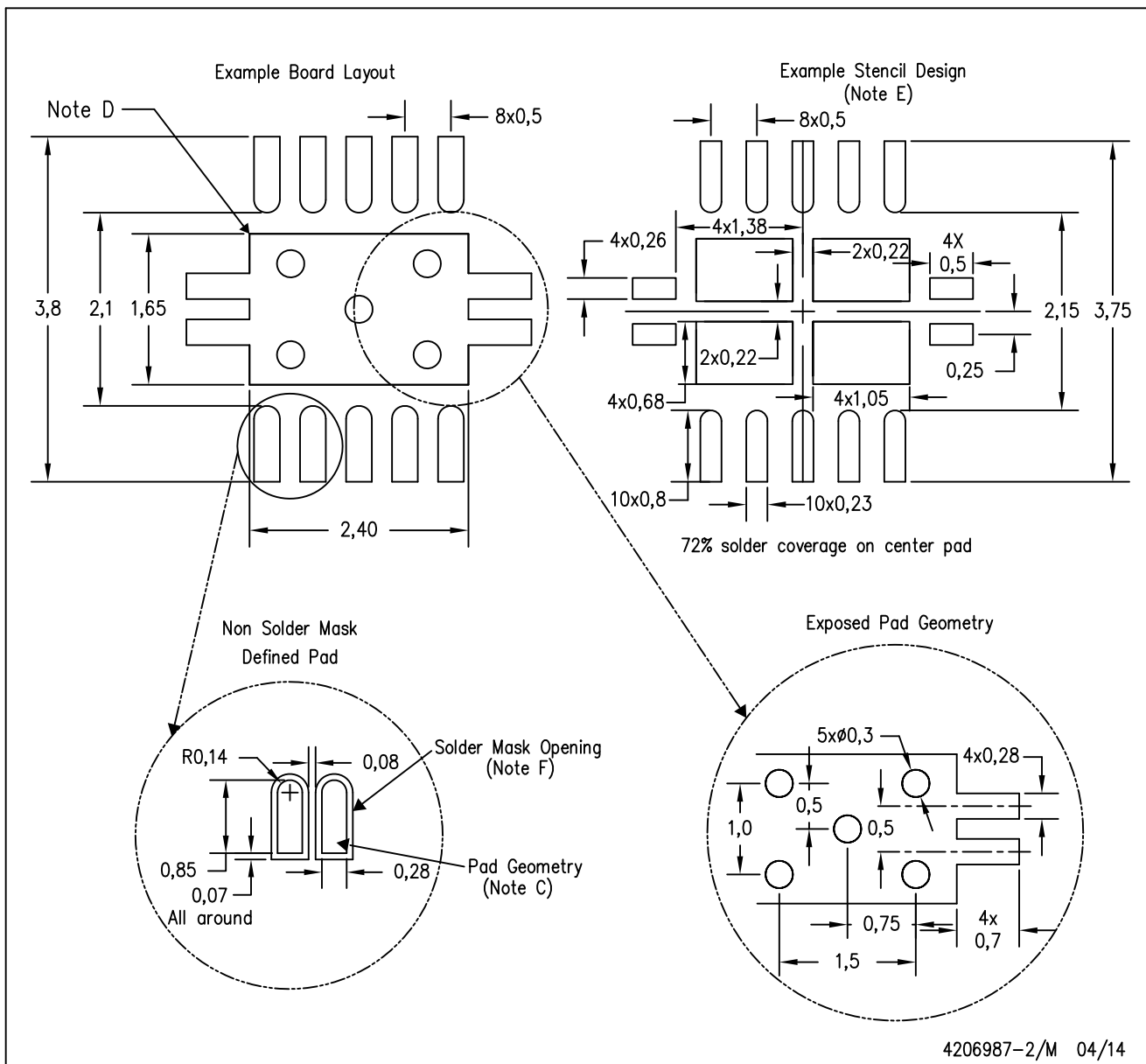
Exposed Thermal Pad Dimensions

4206565-3/U 04/14

NOTE: A. All linear dimensions are in millimeters

DRC (S-PVSON-N10)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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